

GREEN PASTE

Lead-Free Solder Paste: Water Soluble, No-Clean & RMA

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Product Discription

Qualitek's GREEN PASTE is a revolutionary Lead-Free solder paste formulation that makes the conversion to Lead-Free easier than ever to manage. Visually distinguishable, GREEN PASTE helps eliminate the liability of cross contamination and operator confusion between Sn/Pb and Lead-Free paste in a mixed production environment. The paste's green appearance allows operators to readily distinguish it from Sn/Pb paste, whether on a stencil, a spatula, a stencil wipe, or on a printed circuit board. The green color remains until reflowed, leaving normal metallic joint appearance. Post reflow residues, while clear, are UV detectable to further distinguish Lead-Free from Sn/Pb solder on assembled circuit boards. GREEN PASTE is a Patent Pending solution offered only by Qualitek.

Availability

GREEN PASTE is an available option for any of Qualitek's No-Clean and Water Soluble Lead-Free solder paste formulations. Current recommended formulations are:

- No-Clean DSP 865A
- No-Clean DSP 862
- No-Clean DSP 878
- No-Clean DSP 618D (dispensible)
- Water Soluble DSP 798LF
- Water Soluble DSP 718D (dispensible)
- RMA230

Available alloys include typical Sn/Ag/Cu and Sn/Ag, in Type 3, Type 4 and Type 5 meshes.

Technical Information

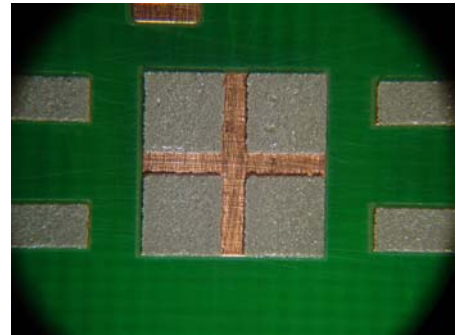
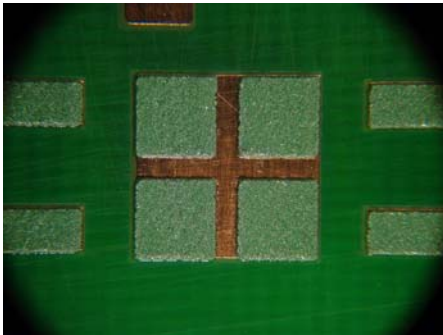
For reference, comparison data and images of the GREEN LF vs. standard color LF paste is given below.

For specific technical information on Physical Properties of the powder, alloys and paste chemistries, such as, SIR, Printing, Reflow, Shelf Life and other application notes please consult the TDS for the particular paste formulation of interest.

GREEN

STANDARD

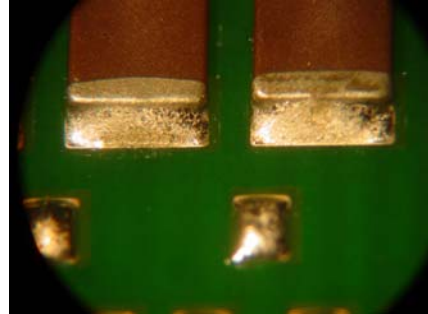
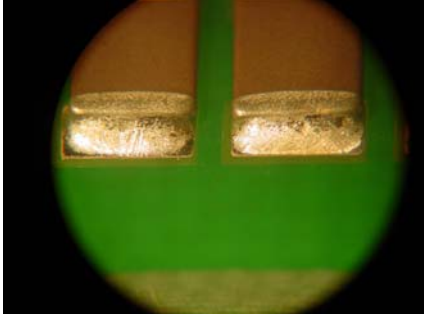
Printing :



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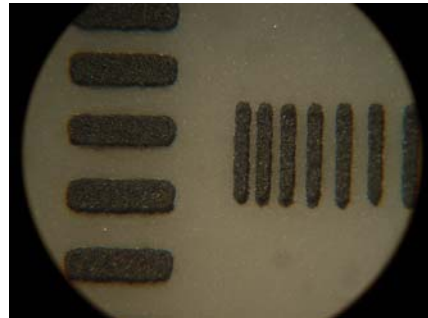
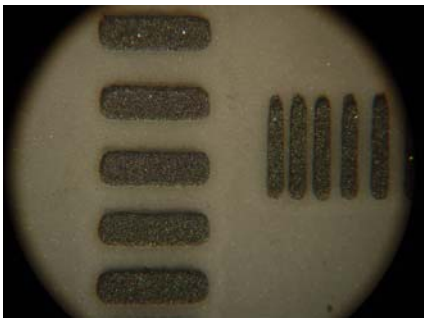
Wetting:



UV Residues: (Black Light)



Hot Slump:

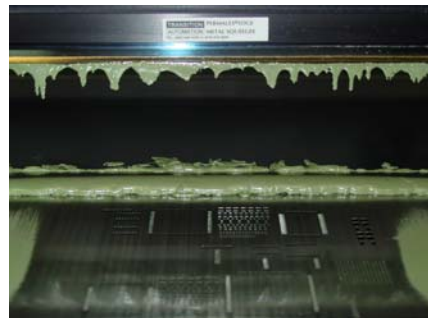


(NOTE: Color dissipates in 150°F test conditions)

On Stencil:



Color at 0 hour

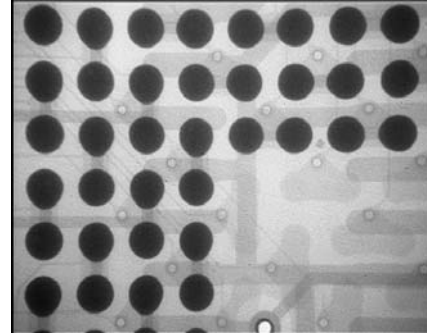
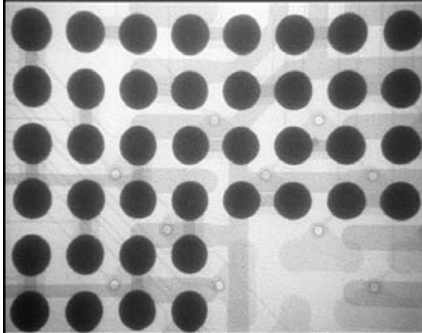


Color after 1 hr. continuous print

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Voids:



SIR: (JSTD-004 and IPC-TM-650 2.6.3.3)

1.91 x 10¹² ohms

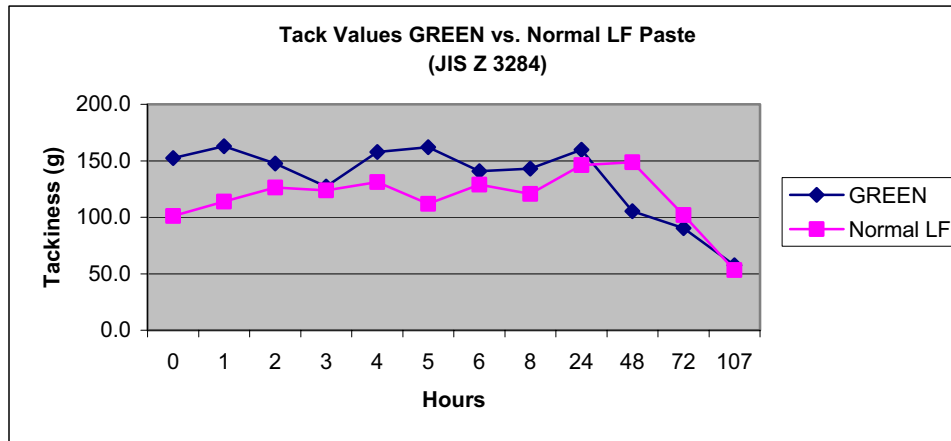
6.44 x 10¹² ohms

Stability: (viscosity after environmental exposure)

Initial 187 kcps @ 24.9°C
After 4 days @ 40°C 190 kcps @ 25°C

190 kcps @ 25°C
191 kcps @ 25°C

Tack Life:



LF965-30 (96.5/3.0/0.5), -325+500, 89% Metal -- Solder Paste Tack		
	GREEN	Standard
Hours	Tackiness (gm)	Tackiness (gm)
0	152.5	101.0
1	162.8	113.9
2	147.7	126.4
3	127.2	123.8
4	157.9	131.2
5	161.9	112.0
6	140.9	128.8
8	143.0	120.6
24	159.9	146.1
48	105.4	148.7
72	90.5	102.1
107	57.5	53.2

Packaging

DEK Proflow Cassette	800 gm
6oz Jar	500 gm
6 oz Cartridge	500-700 gm
12 oz Cartridge	1000-1400gm